kester®

TSF-6592HF

TSF-6592HF IS A NO-CLEAN TACKY SOLDERING FLUX DESIGNED AS A LEAD-FREE SOLUTION FOR AN ARRAY OF LEAD-FREE INTERCONNECT APPLICATIONS FEATURING:

- Compatible with lead-free alloys such as SnAg, SnCu, SnAgCu, SnAgBi
- Reflowable with peak temperatures up to 270°C
- Reflowable in air and nitrogen
- Low voiding
- Bright shiny soldered joints with clear residues
- Aggressive flux on various substrates such as OSP-Cu, immersion finishes and ENIG
- Clear non-tacky residues
- Classified as ROL0 per J-STD-004A
- High tack to minimize skewing of components
- Stencil life of 8+ hours (process dependent)
- Compliant to Bellcore GR-78

Global Headquarters: 800 West Thorndale Avenue, Itasca, IL USA 60143 ▪ Phone: +1 800.2.KESTER ▪ Fax: +1 630.616.4044
Asia-Pacific Headquarters: 61 Ubi Avenue 1 #06-01 UB Point, Singapore 408941 ▪ Phone: +65 6.449.1133 ▪ Fax: +65 6.242.9036
European Headquarters: Ganghofer Strasse 45, 82216 Gernlinden, Germany ▪ Phone: +49 (0) 8142 4785 0 ▪ Fax: +49 (0) 8142 4785 61
Asia Manufacturing: Hengqiao Road, Wujiang Economic Development Zone ▪ Suzhou, Jiangsu Province, China 215200 ▪ Phone: +86 512.82060807 ▪ Fax: +86 512.8206 0808
▪ Website: www.kester.com ▪